

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

1-11. *(cancelled)*

12. *(previously presented)* A lithography system configured to reduce wafer slipping, comprising:

(a) a wafer chuck configured to receive a wafer; and

(b) an expander comprising an expandable annular tube coupled to the wafer chuck and configured to expand the wafer chuck without substantially expanding the wafer, such that an initial stress at an interface between the wafer and the wafer chuck is created.

13. *(canceled)*

14. *(previously presented)* The system of claim 12, wherein said annular tube is coupled to an outer edge of said wafer chuck.

15. *(withdrawn)* The system of claim 13, wherein said annular ring fits within a cavity in said wafer chuck.

16. - 22. *(cancelled)*

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Peter Kochersperger
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23. *(original)* The system of claim 12, wherein said expander is configured to expand said wafer chuck in a uniform manner.